

Wire Saw WS-22

WS-22, works by the lapping method, it is ideal for cutting small samples. The curb loss ranges from 60 μ m to 80 μ m. The damage caused during cutting is very low in comparison to saws using diamond coated wires.



FIELDS OF USE

- * sample preparation in SEM and TEM
- * fault analysis
- * cutting single crystals
- * use instead of spark erosion
- * use in dental research
- * brittle materials with cleavage planes
- * optical windows
- * semiconductors

TECHNICAL DETAILS

- * heavy steel base, weight app. 60 kg
- * works like a frame saw
- * the carrier wire consists of plane tungsten
- * slurry feed: fully automatic
- * oscillation freq.: settable 300 or 400/min
- * sample tilt facility
- * wire guiding during cut
- * curve loss in the range of 70 to 90 μ m
- * surface quality after cutting: as lapped

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